



**DESCRIPTION**

The AM60N04 is available in PDFN8(3.3x3.3) Package.

VDS	RDSON	ID
40V	6.8mΩ	60A

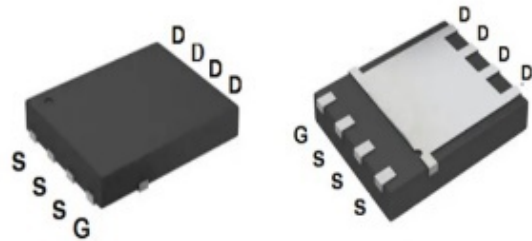
**FEATURE**

- $R_{DS(ON), typ.}=6.8\text{ m}\Omega@V_{GS}=10V$
- $R_{DS(ON), typ.}=10\text{ m}\Omega@V_{GS}=4.5V$
- Fast Switching Mosfet

**APPLICATION**

- High Frequency Switching and Synchronous Rectification.
- DC/DC Converter.

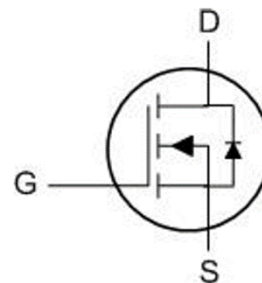
**PIN DESCRIPTION**



**ORDERING INFORMATION**

Package Type	Part Number	
PDFN8(3.3x3.3) SPQ: 5,000pcs/Reel	PJ8S	AM60N04PJ8SR
		AM60N04PJ8SVR
Note	R: Tape & Reel V: Halogen free Package	
AiT provides all RoHS products		

PDFN8 (3.3 x 3.3)



Pin#	Symbol	Function
1, 2, 3,	S	Source
4	G	Gate
5, 6, 7,8	D	Drain



## ABSOLUTE MAXIMUM RATINGS

V <sub>DS</sub> , Drain-Source Voltage	40V	
V <sub>GS</sub> , Gate-Source Voltage	±20V	
I <sub>D</sub> , Continuous Drain Current (1)	T <sub>C</sub> =25°C	60A
	T <sub>C</sub> =100°C	35A
I <sub>DM</sub> (2), Pulsed Drain Current	130A	
EAS (3), Single Pulse Avalanche Energy	48mJ	
I <sub>AS</sub> , Avalanche Current	35A	
P <sub>D</sub> (4), Total Power Dissipation	T <sub>C</sub> =25°C	39W
T <sub>STG</sub> , Storage Temperature Range	-55°C~+150°C	
T <sub>J</sub> , Operating Junction Temperature Range	-55°C~+150°C	
R <sub>θJA</sub> (1), Thermal Resistance Junction-Ambient(Steady State)	60°C/W	
R <sub>θJC</sub> (1), Thermal Resistance Junction-Case	3.2°C/W	

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

(1) The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

(2) The data tested by pulsed, pulse width≤300us, duty cycle≤2%

(3) The EAS data shows Max. rating. The test condition is V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=31A

(4) The power dissipation is limited by 150°C junction temperature

**ELECTRICAL CHARACTERISTICS**T<sub>J</sub>=25°C, unless otherwise noted.

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	40	-	-	V
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =12A	-	6.8	8.3	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	-	10	15	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>DS</sub> =250uA	1	-	3	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 32V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	-	-	1	μA
		V <sub>DS</sub> = 32V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	-	-	5	
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> = 0V	-	-	±100	nA
Gate Resistance	R <sub>g</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	-	1.7	-	Ω
Total Gate Charge (4.5V)	Q <sub>g</sub>	V <sub>D</sub> =20V, V <sub>GS</sub> =4.5V I <sub>D</sub> =12A	-	5.8	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	3	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	1.2	-	
Turn-on Delay Time	T <sub>d(on)</sub>	V <sub>DD</sub> =15V, V <sub>GS</sub> =10V R <sub>G</sub> =3.3Ω, I <sub>D</sub> =1A	-	14.3	-	ns
Rise Time	T <sub>r</sub>		-	5.6	-	
Turn-Off Delay Time	T <sub>d(off)</sub>		-	20	-	
Fall Time	T <sub>f</sub>		-	11	-	
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz	-	690	-	pF
Output Capacitance	C <sub>oss</sub>		-	193	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	38	-	
<b>Diode Characteristics</b>						
Continuous Source Current	I <sub>S</sub>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	-	-	60	A
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	-	-	1	V



## TYPICAL PERFORMANCE CHARACTERISTICS

Fig 1. Typical Output Characteristics

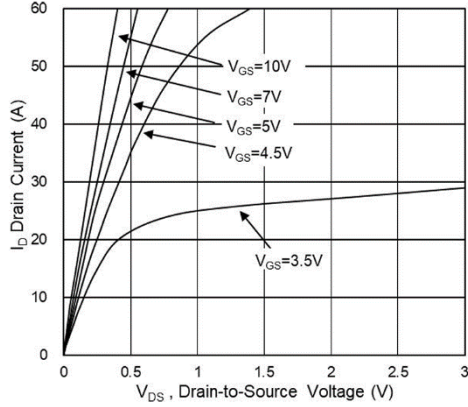


Fig 2. On-Resistance vs. G-S Voltage

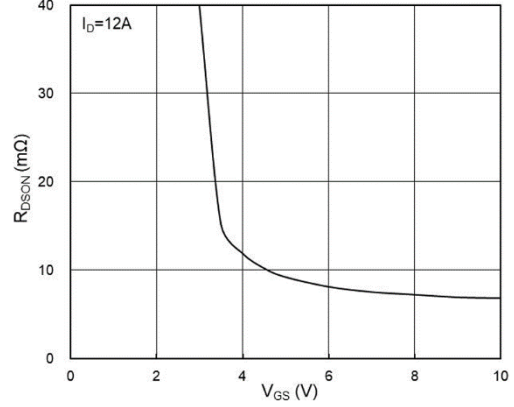


Fig 3. Source Drain Forward Characteristics

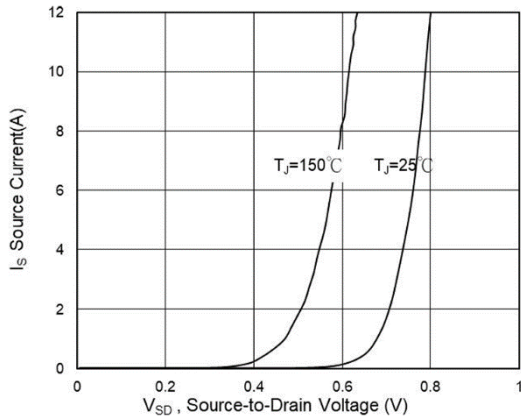


Fig 4. Gate-Charge Characteristics

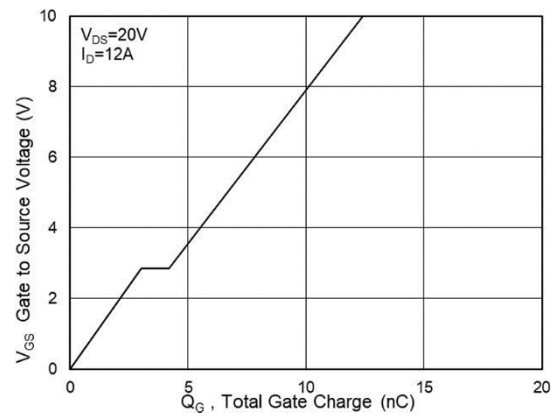


Fig 5. Normalized  $V_{GS(th)}$  vs.  $T_J$

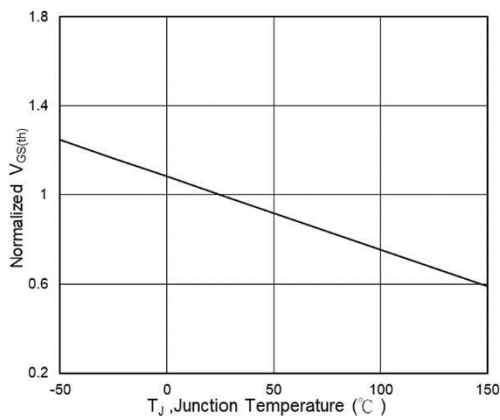


Fig 6. Normalized  $R_{DS(on)}$  vs.  $T_J$

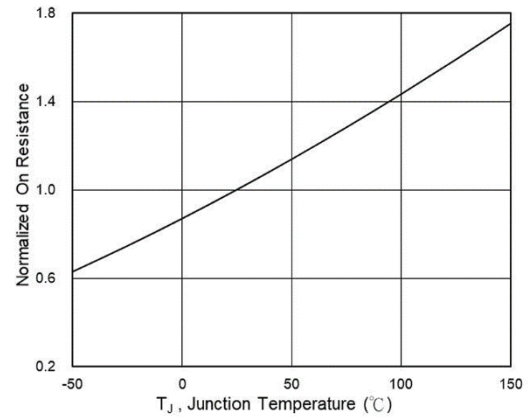




Fig 7. Capacitance

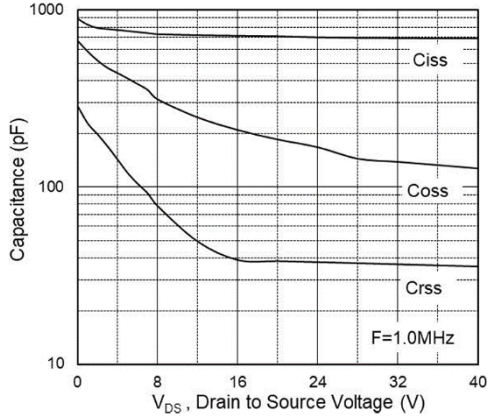


Fig 8. Safe Operating Area

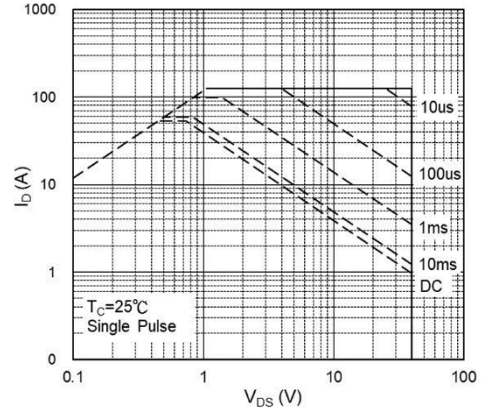


Fig 9. Normalized Maximum Transient Thermal Impedance

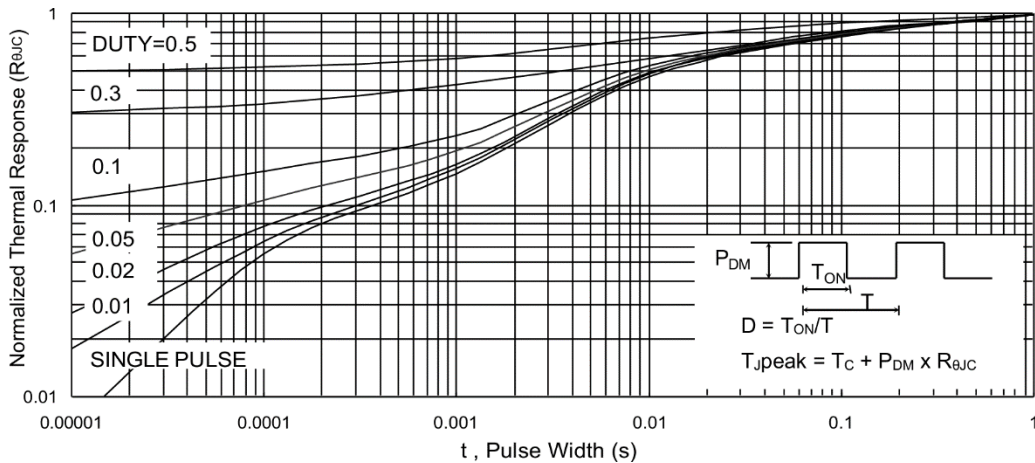


Fig 10. Resistive Switching Test Waveforms

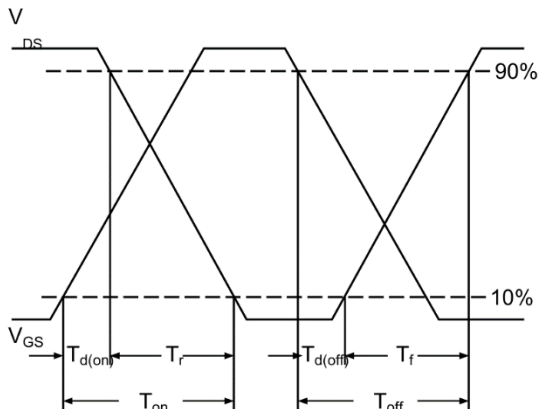
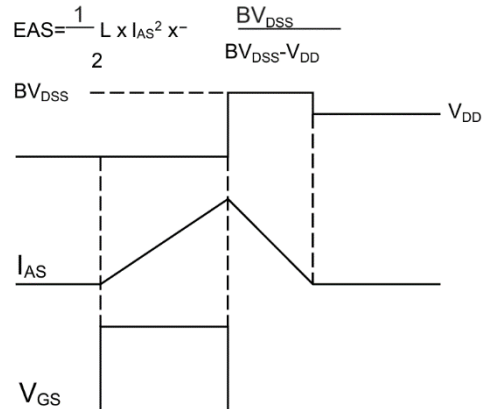


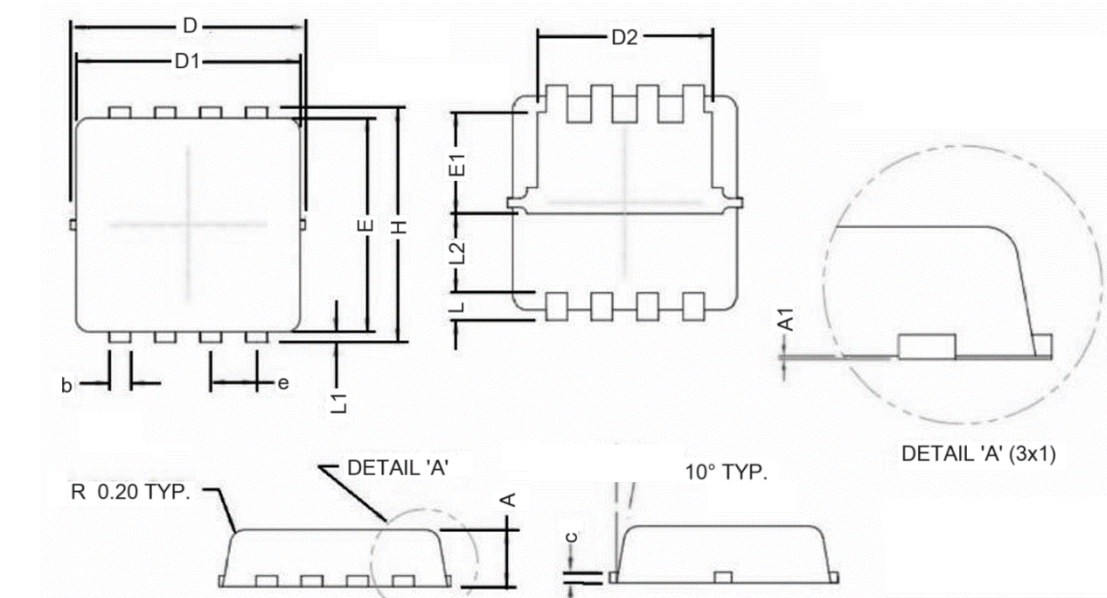
Fig 11. Unclamped Inductive Waveform





**PACKAGE INFORMATION**

Dimension in PDFN8(3.3x3.3) (Unit: mm)



Symbol	Millimeters (mm)	
	Min.	Max.
A	0.700	0.900
A1	0.000	0.050
b	0.240	0.350
c	0.100	0.200
D	3.250	3.400
D1	3.050	3.250
D2	2.400	2.600
E	3.000	3.200
E1	1.350	1.550-
e	0.650 BSC	
H	3.200	3.400
L	0.300	0.500
L1	0.100	0.200
L2	1.130 REF.	



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